



## Description

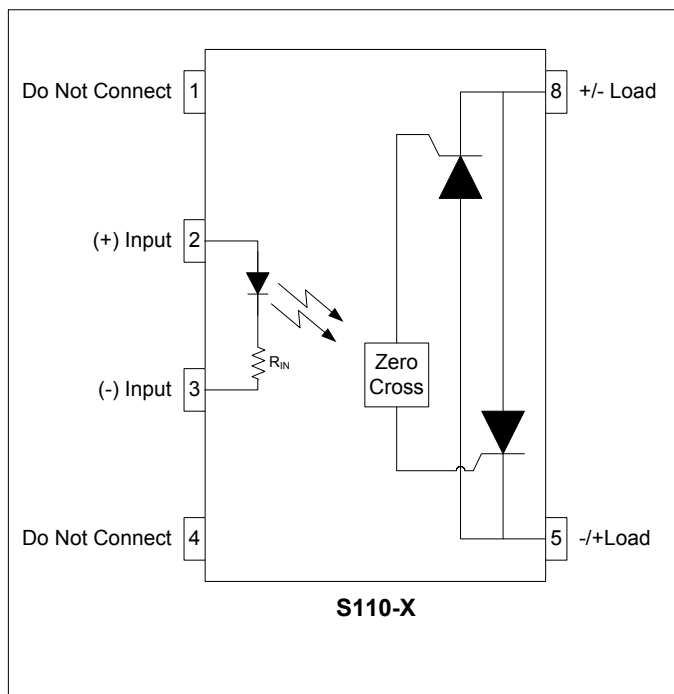
The S110-X is a bi-directional, single-pole, single-throw, normally open multipurpose solid-state relay. The circuit is composed of one input IR LED with a series limiting resistor which activates an optically coupled IC on the output that controls the firing angle of two back-to-back SCRs. This circuit assures no false triggering under most adverse conditions, and a tight zero-volt switching window not exceeding 5V. The S110-X provides high peak load voltage (400V+) and high input-to-output isolation voltage (up to 5kV<sub>RMS</sub>).

The S110-X comes in a compact 8 pin DIP package, making it ideal for high-density board applications.

## Applications

- Valve Control
- Solenoid Control
- Home Appliances
- Metering Equipment
- Heating Elements
- Gas Pump Control Circuitry

## Schematic Diagram



## Features

- Zero-Volt Cross Switching
- Input Series Limiting Resistor (300Ω TYP)
- High Blocking Voltage (400V MIN)
- High Transient Immunity
- 0.8A Maximum Continuous Current
- Low Input Control Current
- Long Life / High Reliability
- RoHS / Pb-Free / REACH Compliant

## Agency Approvals

UL/C-UL: File # E90096  
 VDE: File # 40035191 (EN 60747-5-2)

## Absolute Maximum Ratings

The values indicated are absolute stress ratings. Functional operation of the device is not implied at these or any conditions in excess of those defined in electrical characteristics section of this document. Exposure to absolute Maximum Ratings may cause permanent damage to the device and may adversely affect reliability.

Storage Temperature .....-55 to +125°C  
 Operating Temperature .....-40 to +85°C  
 Continuous Input Current .....50mA  
 Transient Input Current .....500mA  
 Reverse Input Control Voltage .....5V  
 Input Power Dissipation .....40mW  
 Total Power Dissipation .....800mW  
 Solder Temperature – Wave (10sec).....260°C  
 Solder Temperature – IR Reflow (10sec).....260°C

## Ordering Information

Part Number	Description
S110-X	8 pin DIP, (50/Tube)
S110-XH	5kV <sub>RMS</sub> V <sub>ISO</sub> , 8 pin DIP, (50/Tube)
S110-XS	8 pin SMD, (50/Tube)
S110-XHS	5kV <sub>RMS</sub> , 8 pin SMD, (50/Tube)
S110-XSTR	8 pin SMD, Tape and Reel (1000/Reel)
S110-XHSTR	5kV <sub>RMS</sub> , 8 pin SMD, Tape and Reel (1000/Reel)

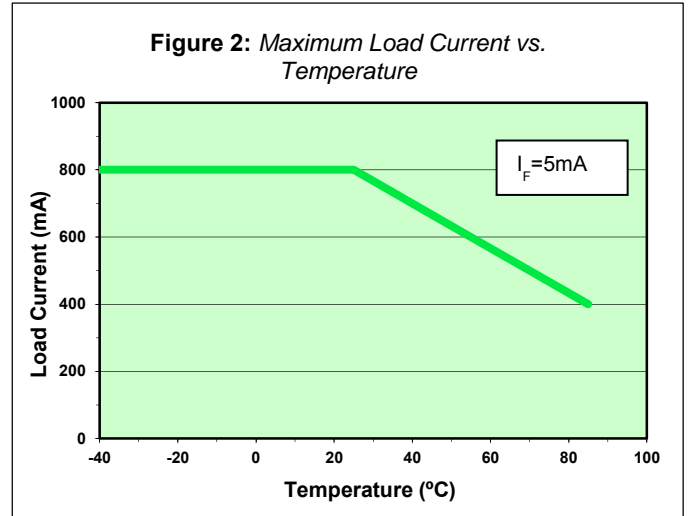
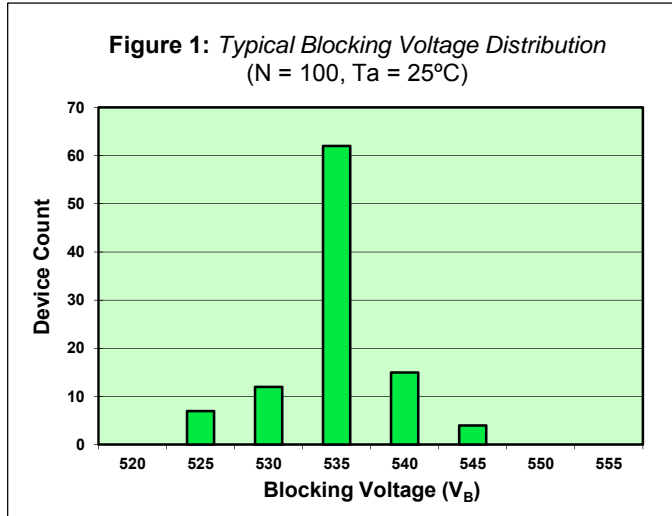
**NOTE: Suffixes listed above are not included in marking on device for part number identification**

**Electrical Characteristics,  $T_A = 25^\circ\text{C}$  (unless otherwise specified)**

Parameter	Symbol	Min.	Typ.	Max.	Units	Test Conditions
<b>Input Specifications</b>						
LED Forward Voltage	$V_F$	-	1.2	1.5	V	$I_F = 10\text{mA}$
LED Reverse Voltage	$BV_R$	5	-	-	V	$I_R = 10\mu\text{A}$
Input Resistor	RIN	-	300	-	$\Omega$	
Trigger (Must Operate) Current <sup>1</sup>	$I_F$	-	3	5	mA	$I_O = I_{O(\text{MAX})}$ [Resistive Load]
Junction Capacitance	$C_J$	-	5	-	pF	$I_F = 0\text{mA}$
<b>Output Specifications</b>						
Blocking Voltage	$V_B$	400	-	-	V	$I_F = 0\text{mA}, I_O = 1\mu\text{A}$
Continuous Load Current	$I_{O(\text{MAX})}$	-	-	0.8	A	$I_F = 5\text{mA}$
Surge Current	$I_{(\text{SURGE})}$	-	-	10	A	$T \leq 16\text{mS}$
Holding Current	$I_{\text{HOLD}}$	-	-	10	mA	$I_F = 5\text{mA}$
On Voltage	$V_{\text{ON}}$	-	-	1.2	V	$I_F = 5\text{mA}, I_O = 0.8\text{A}$
Voltage Across Load at Turn On	-	-	-	5	V	$I_F = 5\text{mA}$
Leakage Current	$I_{\text{leak}}$	-	100	250	$\mu\text{A}$	$I_F = 0\text{mA}, V_O = 250\text{V}$
Thermal Resistance	-	-	80	-	$^\circ\text{C/W}$	
Power Factor <sup>2</sup>	-	-	0.3	-	-	
Critical Rate of Rise (dV/dt) <sup>3</sup>	dV/dt	400	-	-	V/ $\mu\text{S}$	
<b>Coupled Specifications</b>						
Turn-On Time	$T_{\text{ON}}$	-	-	0.5	Cycles	$I_F = 5\text{mA}$
Turn-Off Time	$T_{\text{OFF}}$	-	-	0.5	Cycles	$I_F = 5\text{mA}$
Coupled Capacitance	$C_{\text{COUPLED}}$	-	2	-	pF	
Contact Transient Ratio	-	2,000	7,000	0	V/ $\mu\text{S}$	dV = 50V
<b>Isolation Specifications</b>						
Isolation Voltage (-H Option)	$V_{\text{ISO}}$	3750 5000	- -	- -	$V_{\text{RMS}}$	$\text{RH} \leq 50\%, t=1\text{min}$
Input-Output Resistance	$R_{\text{I-O}}$	-	$10^{12}$	-	$\Omega$	$V_{\text{I-O}} = 500V_{\text{DC}}$

**NOTES:**

- 1) Resistive load. For inductive loads, higher drive current is recommended
- 2) Snubber circuits may be required for lower power factors
- 3) This is for static dV/dt.

**S110-X Performance & Characteristics Plots,  $T_A = 25^\circ\text{C}$  (unless otherwise specified)**

**ZERO-VOLT SWITCHING**

This solid state relay has been designed with a driver circuit that controls the operation of two back-to-back silicon controlled rectifiers (SCRs), each responsible for one half of the AC cycle. If an AC signal is examined, the turn on, turn off and zero-volt switching can be seen. Figure 3 shows a typical 60 HZ, 120VAC signal with a corresponding relay input signal:

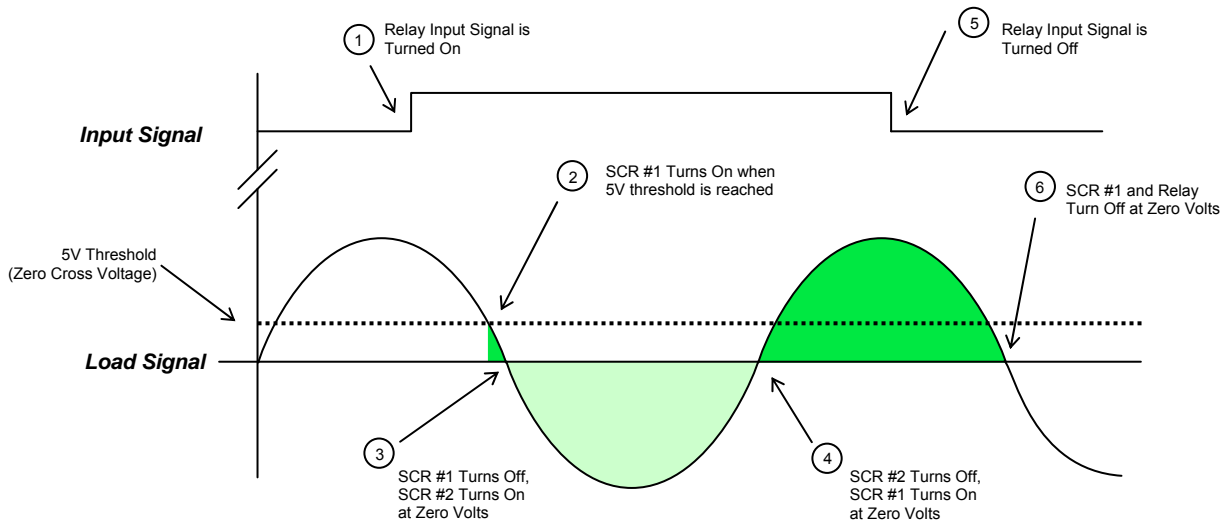
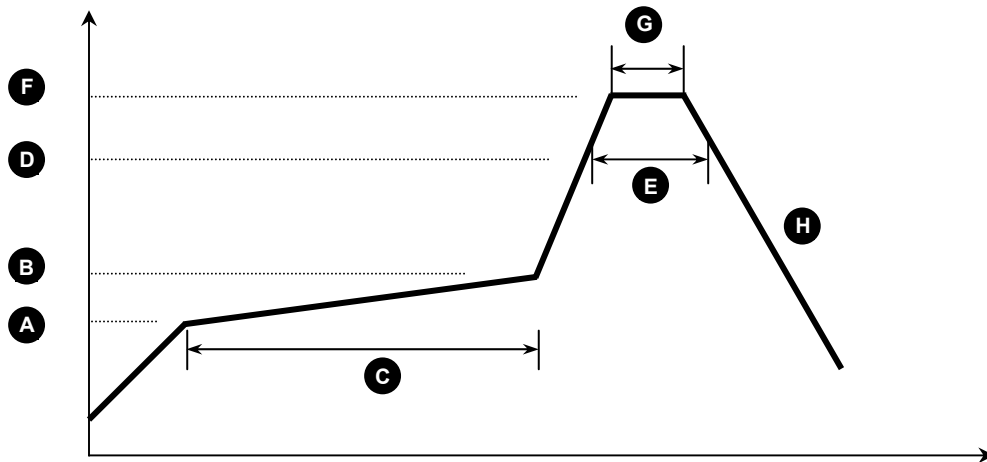


Figure 3: Zero-Volt Switching Cycle

Figure 3 shows the sequence of zero-volt switching operation. At Stage 1, an input signal is applied to the relay. The relay will not turn on until the threshold voltage of 5V is reached. Once this point is reached (Stage 2), SCR #1 (designated as the SCR which controls positive AC voltage) turns on. However, SCR #1 only conducts for an instant, as the cycle quickly crosses zero. At this point (Stage 3), SCR #1 will turn off and SCR #2 (negative AC voltage) turns on. Likewise, at the next zero cross (Stage 4), SCR #2 will turn off and SCR #1 conducts again. Even though the input signal is terminated at Stage 5, the relay will continue to conduct (typical SCR behavior) until Stage 6, when SCR #1 crosses zero and ceases to conduct. Please note that turn on can likewise begin on the negative phase of the AC cycle with a -5V threshold, though only the positive phase is shown here.

**S110-X Solder Reflow Temperature Profile Recommendations**
**(1) Infrared Reflow:**

Refer to the following figure as an example of an optimal temperature profile for single occurrence infrared reflow. Soldering process should not exceed temperature or time limits expressed herein. Surface temperature of device package should not exceed 250°C:



Process Step	Description	Parameter
A	Preheat Start Temperature (°C)	150°C
B	Preheat Finish Temperature (°C)	180°C
C	Preheat Time (s)	90 - 120s
D	Melting Temperature (°C)	230°C
E	Time above Melting Temperature (s)	30s
F	Peak Temperature, at Terminal (°C)	260°C
G	Dwell Time at Peak Temperature (s)	10s
H	Cool-down (°C/s)	<6°C/s

**(2) Wave Solder:**

Maximum Temperature: 260°C (at terminal)  
 Maximum Time: 10s  
 Pre-heating: 100 - 150°C (30 - 90s)  
 Single Occurrence

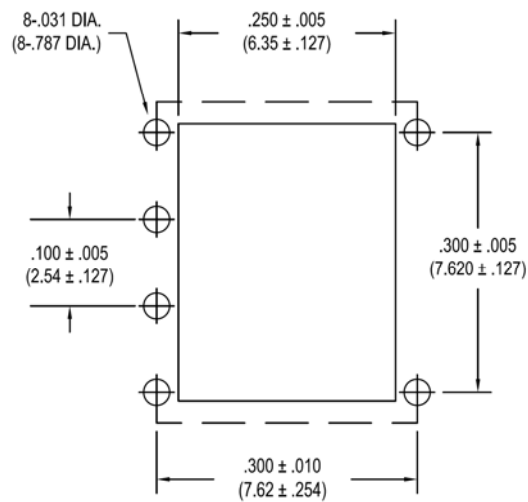
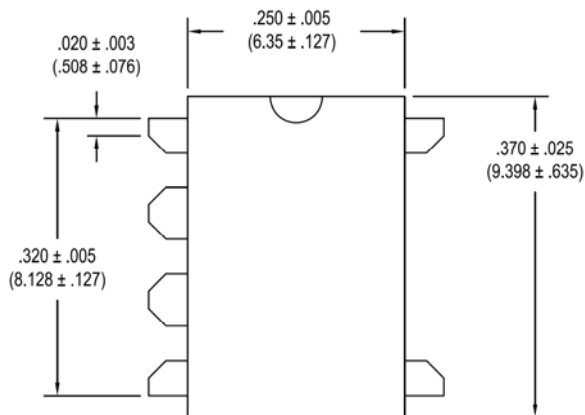
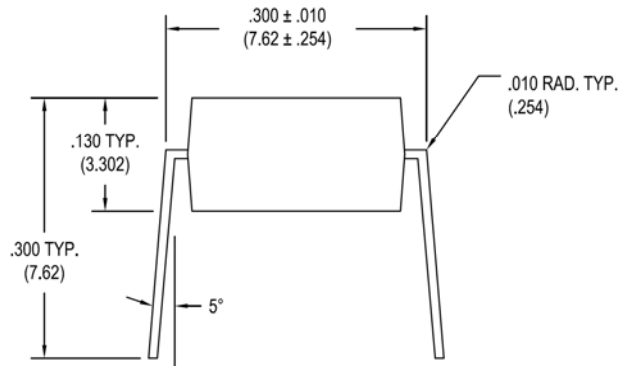
**(3) Hand Solder:**

Maximum Temperature: 350°C (at tip of soldering iron)  
 Maximum Time: 3s  
 Single Occurrence

**S110-X Package Dimensions**

8 PIN DIP Package

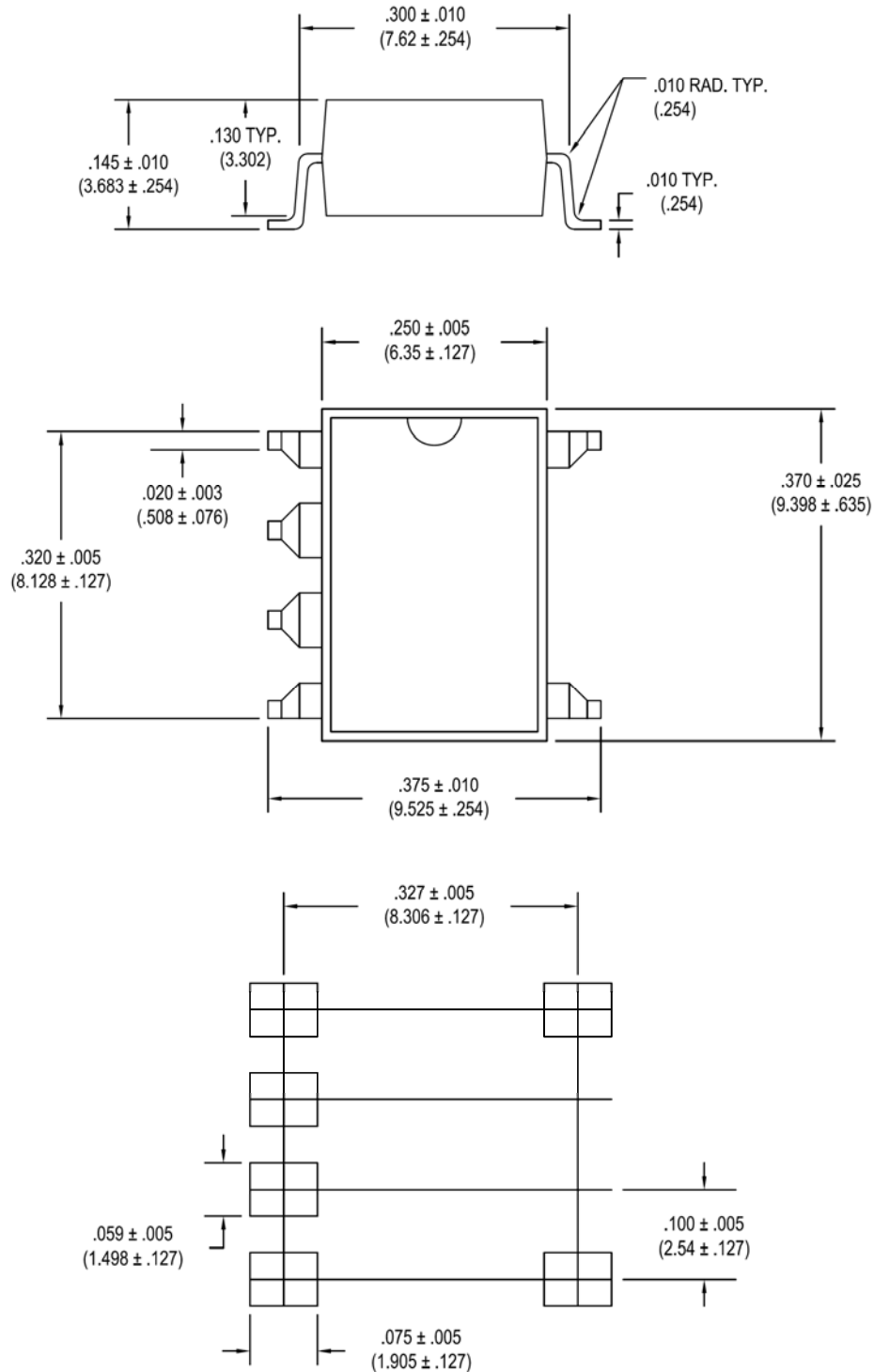
**Note:** All dimensions in inches ["] with millimeters in parenthesis ( )



**S110-X Package Dimensions**

8 PIN SMD Surface Mount Package (-S)

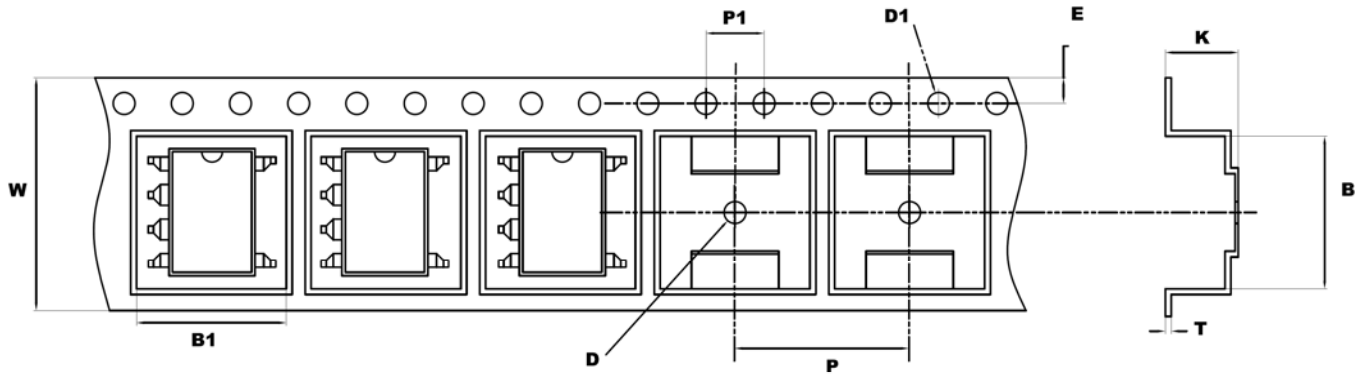
**Note:** All dimensions in inches ["] with millimeters in parenthesis ( )



**S110-X Package Dimensions**

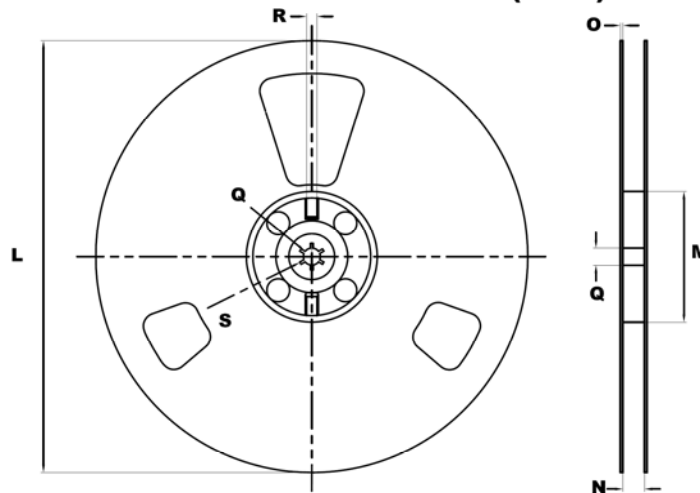
8 PIN SMD Tape &amp; Reel (-STR)

**Note:** All dimensions in millimeters

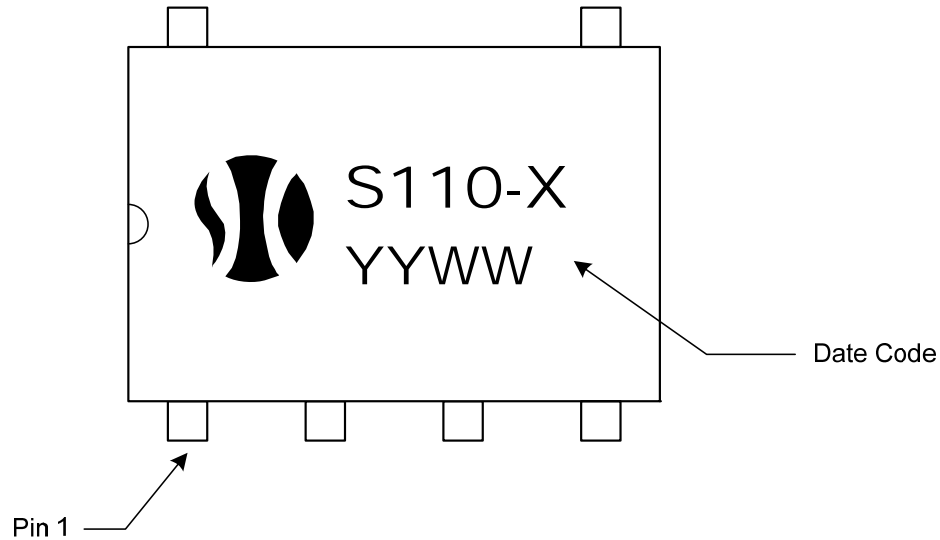
**Outline and Dimension (Tape)**


Direction of Feed →

W	B	B1	P	P1	K	E	T	D	D1
16.00 ±0.1	10.50 ±0.1	10.30 ±0.1	12.00 ±0.1	4.00 ±0.1	5.00 ±0.1	1.75 ±0.1	0.40 ±0.1	1.50 ±0.1	1.50 ±0.1

**Outline and Dimensions (Reel)**

**Packaging: 1,000 pcs / reel**

L	M	N	O	Q	R	S
330.00	100.00	16.40 +0.2	2.00 ±0.1	13.00 ±0.2	2.00	10.00

**S110-X Package Marking**

**S110-X Package Weights**

Device	Single Unit	Full Tube (50pcs)	Full Pouch (10 tubes)	Full Reel (1000pcs)
S110-X(H)	0.54	48	490	-
S110-X(H)S	0.53	46	470	-
S110-X(H)STR	0.53	-	-	952

**Note:** All weights above are in GRAMS, and include packaging materials where applicable

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